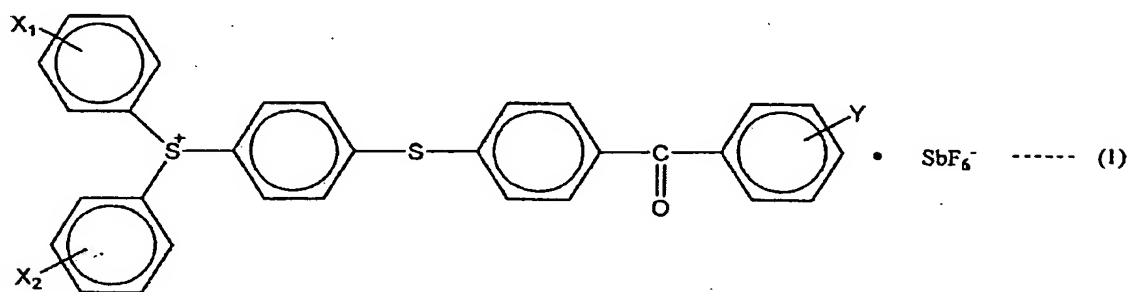


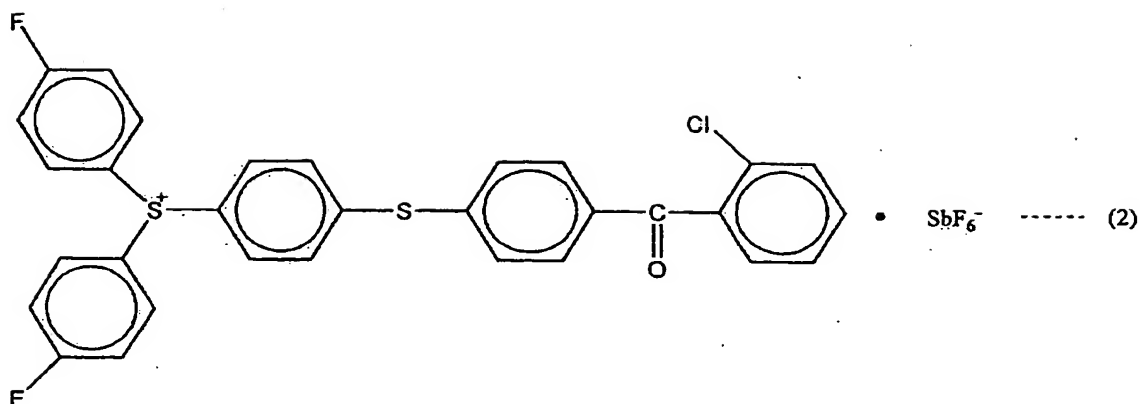
CLAIMS

1. A photosensitive resin composition comprising:
 a multi-functional epoxy resin; and
 a cation polymerization initiator represented by general formula (1) shown below:



(in the formula, X₁ and X₂ indicate a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond, respectively, and they may be identical to or different from one another, and Y indicates a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond).

2. The photosensitive resin composition according to claim 1, wherein the multi-functional epoxy resin is a multi-functional bisphenol A novolak epoxy resin, and the cation polymerization initiator is a compound represented by chemical formula (2) shown below:



3. The photosensitive resin composition according to claim 1, further comprising a linear polymeric 2-functional epoxy resin.

4. The photosensitive resin composition according to claim 1, further comprising a naphthol sensitizer.

5. The photosensitive resin composition according to claim 1, further comprising γ -butyrolactone.

6. A photosensitive resin composition laminate comprising:
 a photosensitive resin composition layer obtained from the photosensitive resin composition according to claim 1; and
 a protective film,
 wherein at least one side of the photosensitive resin composition layer is protected with the protective film.

7. A method of forming a pattern comprising the steps of:
 applying the photosensitive resin composition according to claim 1 on a desired base and then drying the photosensitive resin composition;
 exposing a radiation beam on a photosensitive resin composition layer to form given resin patterns;
 developing the beam-exposed photosensitive resin composition layer; and

heat-treating the resulting resin patterns to yield cured resin patterns of given shapes.

8. A method of forming a pattern comprising the steps of:
 - peeling the protective film away from the photosensitive resin composition laminate according to claim 6;
 - attaching a resulting photosensitive resin composition layer on a desired base;
 - exposing a radiation beam on the photosensitive resin composition layer to form a given pattern;
 - developing the beam-exposed photosensitive resin composition layer; and
 - heat-treating the resulting resin patterns to yield cured resin patterns of given shapes.